Advances in Artificial Intelligence (AI)-Driven Data Analytics

Guest Editors:

Prof. Dr. Hong-Jie Dai

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Deadline for manuscript submissions:
closed (31 March 2023)

Message from the Guest Editors

Dear Colleagues,

We invite submissions to this Special Issue on Advances in Artificial Intelligence (AI)-Driven Data Analytics.

Nowadays, AI has a wide range of applications in our daily lives, playing an essential role in data-driven decision making. Industries such as manufacturing, healthcare social media and creative industries generate and manipulate a vast amount of data, and so there is an increasing need to leverage AI-driven data analytics for data interpretation. In this Special Issue, we invite submissions exploring the research and application of AI in data analysis across a variety of disciplines. In particular, we are interested in the research of applying AI to typical manufacturing problems and emerging AI technologies employed in the field of social media, healthcare and creative industries. These techniques include, but are not limited to, data preprocessing, data engineering, data visualization, machine learning, data mining and text mining.

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Guest Editors

Special Issue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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